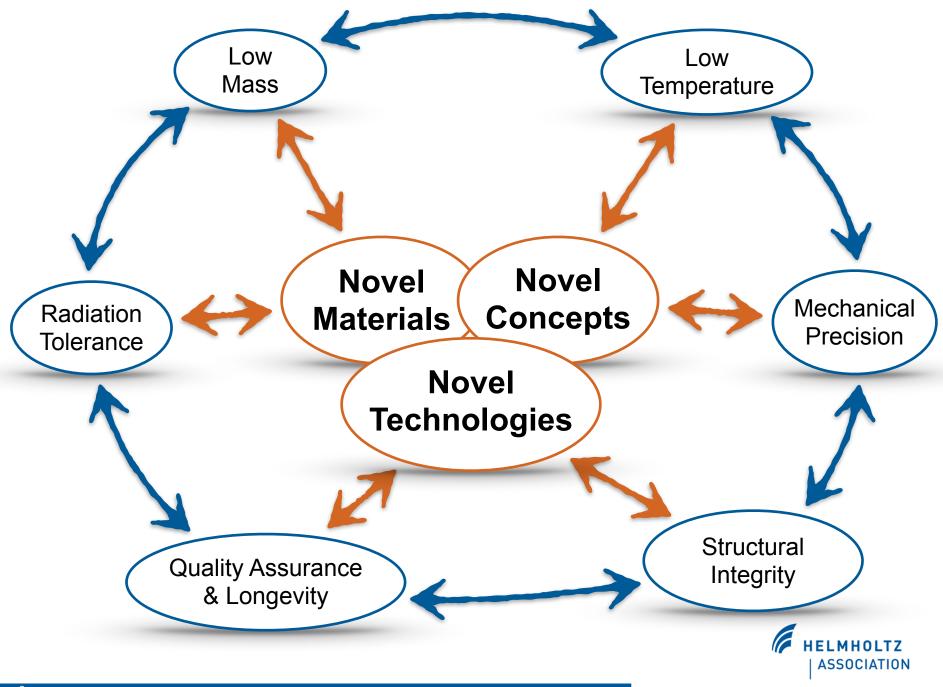


Future Detectors -The Engineering Challenges





Andreas Mussgiller

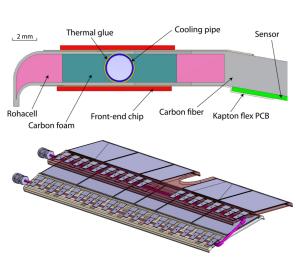
Low Mass System Designs

- essential for reconstruction performance
- future detectors demand lightweight or even ultra lightweight support structures
 - including cooling and cabling



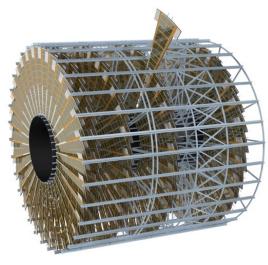
Belle II Vertex Detector

- 2 layers
- 10 cm length
- 2.8/4.4 cm diameter
- 0.21% X_0 for inner layer



Panda MVD Barrel

- 4 layers
- 31 cm length
- 27 cm diameter
- < 10% X₀ for most parts of the acceptance



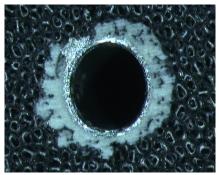
ATLAS Strip Tracker Endcap

- 35 m² of silicon
- 1.7 m length
- 2 m diameter
- 180 kg mass

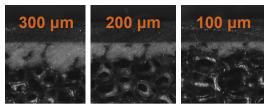


Low Temperature Operation

- · higher granularity detectors and more functionality in front-end
 - higher front-end power to be cooled away
- radiation levels at e.g. HL-LHC require operation at -20 °C
 - minimise leakage currents and noise
 - avoid thermal runaway
- novel materials and technologies can combine demands of a low mass system design with thermal management needs



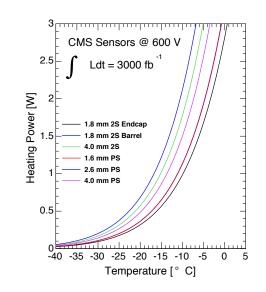
Ti-Pipe embedded in C-Foam

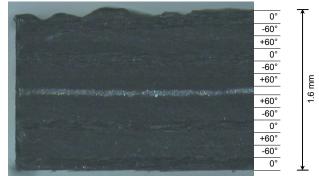


C-Foam glueing test to optimize amount of glue



ATLAS Endcap Petal Prototype





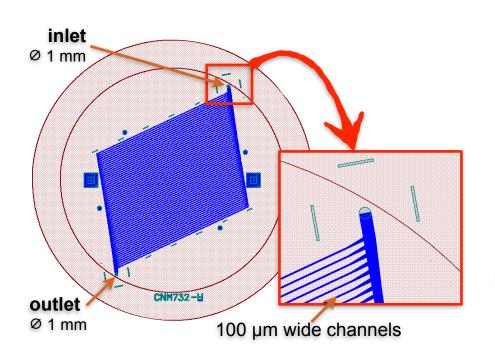
Graphite foil laminated into CFRP combines structural with thermal management material



Andreas Mussgiller

Novel Cooling Concepts

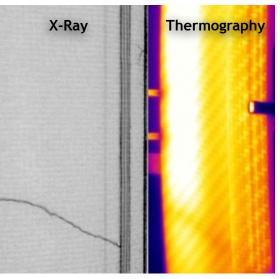
- state-of-the-art cooling systems for detectors rely on heat conduction
- · micro-fabricated cooling channels embedded in thin silicon substrates
 - bring coolant to where the heat is actually generated
 - no CTE mis-match between sensitive element and cooling
 - no stress on sensor and no deformation
 - → ideal for both X-Ray imagers and HEP
 - Helmholtz-Cube could be test bench





Longevity Engineering

- inner tracking detectors in HEP experiments are typically inaccessible for repair
- · a lifetime of ten or more years has to be taken into account
 - · already in the design phase and
 - ensured during large scale productions
- engineering design has to guarantee
 - quality of detector components in yield and longevity
 - tolerance to expected radiation levels (e.g. glues)
 - structural integrity (e.g. for up to 100 thermal cycles)



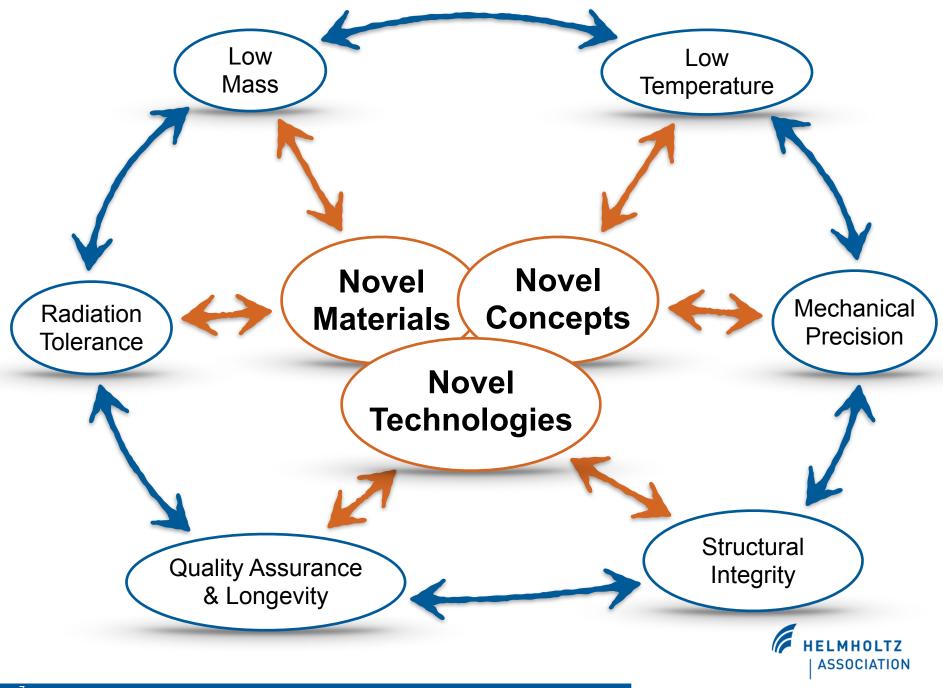
Panda MVD Strip Barrel Stave

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Optical Inspection of a TPC Field Cage





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